



***The 2022 IEEE VLSI Symposium on Technology & Circuits, Now Merged as a Single Event, Announces Call for Papers on the Theme: “Technology & Circuits for the Critical Infrastructure of the Future”***

HONOLULU, HI (January 4, 2021) – Now in its 42<sup>nd</sup> year of delivering a unique convergence of technology and circuits for the microelectronics industry, the Symposia on VLSI Technology & Circuits will be merged into one Symposium to maximize the synergy across both domains. The newly merged 2022 IEEE VLSI Symposium on Technology & Circuits has announced a call for papers around the theme: “Technology & Circuits for the Critical Infrastructure of the Future.” The five-day hybrid event, combining both live sessions onsite at the Hilton Hawaiian Village, as well as on-demand access to selected presentations and panel sessions, is scheduled from June 13 – 17, 2022 in Honolulu, HI. The Symposium will feature advanced VLSI technology developments, innovative circuit design, and the applications they enable, such as artificial intelligence, machine learning, IoT, wearable/implantable biomedical applications, big data, cloud / edge computing, virtual reality (VR) / augmented reality (AR), robotics, and autonomous vehicles.

The deadline for paper submissions to the merged Symposium is February 7, 2022 at 23:59 PST.

Complete details for paper submission can be found online at: <https://www.vlsisymposium.org/first-announcement-and-call-for-papers/>

The **IEEE VLSI Symposium on Technology & Circuits** seeks papers focusing on technical innovation and advances in the following areas:

- Advanced CMOS devices and technologies
- Advanced packaging, heterogeneous integration
- Beyond-CMOS technologies and platforms, such as quantum devices and computing systems
- Biomedical devices, circuits and systems
- Data converters
- Device and system reliability
- Devices and accelerators for machine learning
- Device physics, characterization and modelling
- Digital circuits, hardware, signal integrity and IOs
- DTCO and design enablement
- Frequency generation and clock circuits
- Memory technologies, devices, circuits and architectures
- Power, analog and mixed-signal devices, and circuits
- Process technology
- Processors and SoCs

- Sensors, imagers, IoT, MEMS, display circuits
- Wireless and RF devices circuits and systems
- Wireline and optical transceivers; optical interconnect and processors
- **NEW:** Innovative systems, designed with FPGAs and COTS components

The weeklong Symposium will continue its reputation as the microelectronics industry's premiere international conference integrating technology, circuits, and systems with a range and scope unlike any other conference. In addition to the technical presentations, the Symposium program will feature a demonstration session, evening panel discussions, joint focus sessions, short courses, workshops, and a special forum session that provides a focused discussion on a specific topic relevant to the Symposium theme.

Special events at the Symposium include mentoring events for Women in Engineering and Young Professionals, sponsored by the IEEE Electron Devices Society and the Solid State Circuits Society.

Best Student Paper Awards for each track Symposium are chosen based on the quality of the papers and presentations. The recipients will receive a monetary award, travel cost support, and a certificate. For a paper to be reviewed for this award, the lead author and presenter of the paper must be enrolled as a full-time student at the time of submission, and must indicate on the web submission form that the paper is a student paper.

### **Further Information and Official Call for Papers**

Visit: <http://www.vlsisymposium.org>.

### **Sponsoring Organizations**

The IEEE VLSI Symposium on Technology & Circuits is sponsored by the the IEEE Electron Devices Society, in cooperation with the IEEE Solid State Circuits Society and Japan Society of Applied Physics, in cooperation with the Institute of Electronics, Information and Communication Engineers.

### **Media Contacts**

(North America and EU)

BtB Integrated Marketing – Chris Burke, co-Media Relations Director

E-mail: [chris.burke@btbmarketing.com](mailto:chris.burke@btbmarketing.com)

(Japan and Asia)

Secretariat for VLSI Symposia c/o JTB Communication Design, Inc.

Tokyo, Japan

E-mail: [vlsisymp@jtbc.com](mailto:vlsisymp@jtbc.com)